

MH5128ABNA-70L,-85L,-10L,-12L,-15L / MH5128ABNA-70H,-85H,-10H,-12H,-15H

4194304-BIT (524288-WORD BY 8-BIT) CMOS STATIC RAM

DESCRIPTION

The MH5128ABNA is a 4194304-bits CMOS static RAM module organized as 524288-words by 8-bits. It consists of four industry standard 128K × 8 static RAMs (M5M51008AVP, RV) and two decoders.

The stand-by current is low enough for a battery back-up application. It is mounted a TSOP package.

FEATURES

Type name	Access time (max)	Power supply current	
		Active (max)	Stand-by (max)
MH5128ABNA-70L MH5128ABNA-85L MH5128ABNA-10L MH5128ABNA-12L MH5128ABNA-15L	70ns 85ns 100ns 120ns 150ns	180mA	250 μ A (V _{CC} = 3.0V)
MH5128ABNA-70H MH5128ABNA-85H MH5128ABNA-10H MH5128ABNA-12H MH5128ABNA-15H	70ns 85ns 100ns 120ns 150ns		90 μ A (V _{CC} = 3.0V)

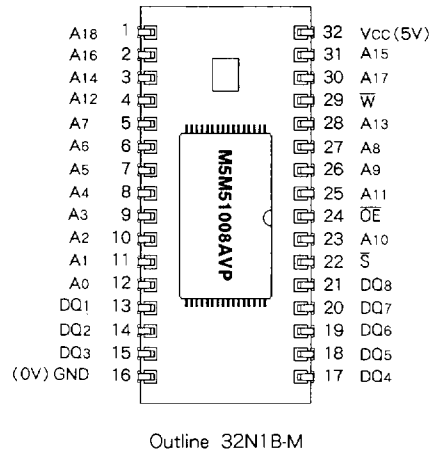
- Single +5V power supply
- No clocks, no refresh
- Data-hold on +2V power supply
- Three-state outputs : OR-tie capability
- Simple memory expansion by \bar{S}
- \bar{OE} prevents data contention in the I/O bus
- Common data I/O

APPLICATION

Small capacity memory units

PIN CONFIGURATION (TOP VIEW)

(Both side, 2-Layer)

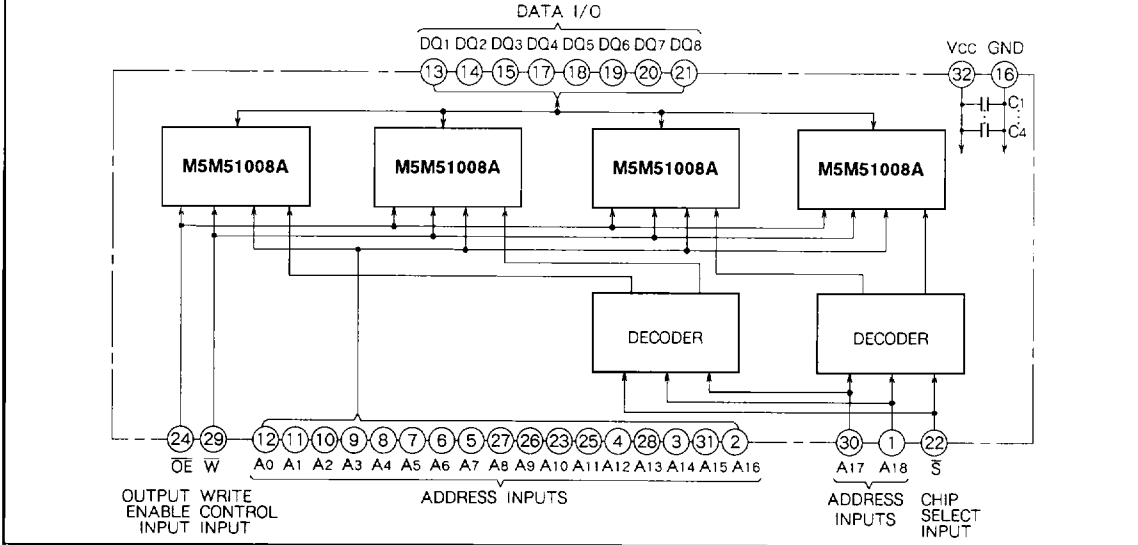


FUNCTION

The operation mode of the MH5128ABNA is determined by a combination of the device control inputs \bar{S} , \bar{W} and \bar{OE} . Each mode is summarized in the function table.(see next page)

A write cycle is executed whenever the low level \bar{W} overlaps with the low level \bar{S} . The address must be set up before the write cycle and must be stable during the entire cycle. The data is latched into a cell on the trailing edge of \bar{W} , \bar{S} , whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The output

BLOCK DIAGRAM



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enable \overline{OE} directly controls the output stage. Setting the \overline{OE} at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.

A read cycle is executed by setting \overline{W} at a high level and \overline{OE} at a low level while \overline{S} are in an active state.

When setting \overline{S} at a high level, the chip is in a non-selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by \overline{S} . The power supply current is

reduced as low as the stand-by current which is specified as I_{CC3} or I_{CC4} , and the memory data can be held +2V power supply, enabling battery back-up operation during power failure or power-down operation in the non-selected mode.

FUNCTION TABLE

\overline{S}	\overline{W}	\overline{OE}	Mode	DQ	I_{CC}
H	X	X	Non-selection	High-impedance	Stand-by
L	L	X	Write	D_{IN}	Active
L	H	L	Read	D_{OUT}	Active
L	H	H		High-impedance	Active

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V_{CC}	Supply voltage	With respect to GND	-0.3 ~ 7	V
V_I	Input voltage		-0.3 ~ $V_{CC} + 0.3$	V
V_O	Output voltage		0 ~ V_{CC}	V
P_d	Power dissipation	$T_a = 25^\circ\text{C}$	700	mW
T_{opr}	Operating temperature		0 ~ 70	$^\circ\text{C}$
T_{stg}	Storage temperature		-40 ~ 100	$^\circ\text{C}$

RECOMMENDED OPERATING CONDITIONS ($T_a = 0 \sim 70^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min	Typ	Max	
V_{CC}	Supply voltage	4.5	5	5.5	V
GND	Supply voltage		0		V
V_{IL}	Low input voltage	-0.3		0.8	V
V_{IH}	High input voltage	2.2		$V_{CC} + 0.3$	V

ELECTRICAL CHARACTERISTICS ($T_a = 0 \sim 70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V_{IH}	High input voltage		2.2		$V_{CC} + 0.3$	V
V_{IL}	Low input voltage		-0.3		0.8	V
V_{OH}	High output voltage	$I_{OH} = -1\text{mA}$	2.4			V
V_{OL}	Low output voltage	$I_{OL} = 2\text{mA}$			0.4	V
I_I	Input leakage current	$V_I = 0 \sim V_{CC}$			± 4	μA
I_O	Output current in off-state	$\overline{S} = V_{IH}$ or $\overline{OE} = V_{IH}$, $V_{I/O} = 0 \sim V_{CC}$			± 4	μA
I_{CC1}	Active supply current (AC. MOS level)	$\overline{S} \leq 0.2V$, output open other input $\leq 0.2V$ or $\geq V_{CC} - 0.2V$ Min. cycle		110	160	mA
I_{CC2}	Active supply current (AC. TTL level)	$\overline{S} = V_{IL}$, output open other input = V_{IL} or V_{IH} Min. cycle		150	200	mA
I_{CC3}	Stand-by supply current	$\overline{S} \geq V_{CC} - 0.2V$, $A_{17} \sim A_{18} \leq 0.2V$ or $\geq V_{CC} - 0.2V$ other inputs = $0 \sim V_{CC}$	ABNA-L		450	μA
			ABNA-H	12	130	μA
I_{CC4}	Stand-by supply current	$\overline{S} = V_{IH}$, $A_{17} \sim A_{18} = V_{CC}$ or GND other inputs = $0 \sim V_{CC}$			70	mA
C_i	Input capacitance ($T_a = 25^\circ\text{C}$)	$V_I = \text{GND}$, $V_o = 25\text{mVrms}$, $f = 1\text{MHz}$			50	pF
C_o	Output capacitance ($T_a = 25^\circ\text{C}$)	$V_o = \text{GND}$, $V_i = 25\text{mVrms}$, $f = 1\text{MHz}$			40	pF

Note 1. Direction for current flowing into IC is indicated as positive (no mark).
2. Typical value is $V_{CC} = 5V$, $T_a = 25^\circ\text{C}$.

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AC ELECTRICAL CHARACTERISTICS ($T_a = 0 \sim 70^\circ\text{C}$, $V_{cc} = 5V \pm 10\%$, unless otherwise noted)

MEASUREMENT CONDITIONS

Input pulse levels..... $V_{IH} = 3.0V$, $V_{IL} = 0V$

Input rise and fall time.....5ns

Reference levels..... $V_{OH} = V_{OL} = 1.5V$

Transition is measured $\pm 500\text{mV}$ from steady state voltage.(for t_{en} , t_{dis})

Output loads Fig. 1, $C_L = 100\text{pF}$ (-10L, -12L, -15L, -10H, -12H, -15H)

$C_L = 30\text{pF}$ (-70L, -85L, -70H, -85H)

$C_L = 5\text{pF}$ (for t_{en} , t_{dis})

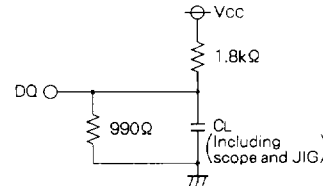


Fig. 1 Output load

SWITCHING CHARACTERISTICS ($T_a = 0 \sim 70^\circ\text{C}$, $V_{cc} = 5V \pm 10\%$, unless otherwise noted)

Read cycle

Symbol	Parameter	Limits										Unit
		MH5128-70		MH5128-85		MH5128-10		MH5128-12		MH5128-15		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{CR}	Read cycle time	70		85		100		120		150		ns
$t_{a(A)}$	Address access time		70		85		100		120		150	ns
$t_{a(S)}$	Chip select access time		70		85		100		120		150	ns
$t_{a(OE)}$	Output enable access time		30		35		45		50		60	ns
$t_{dis(S)}$	Output disable time after \bar{S} high		35		40		45		50		55	ns
$t_{dis(OE)}$	Output disable time after \bar{OE} high		20		25		30		35		40	ns
$t_{en(S)}$	Output enable time after \bar{S} low	5		5		5		5		5		ns
$t_{en(OE)}$	Output enable time after \bar{OE} low	5		5		5		5		5		ns
$t_{v(A)}$	Data valid time after address change	5		10		10		10		10		ns

TIMING REQUIREMENTS ($T_a = 0 \sim 70^\circ\text{C}$, $V_{cc} = 5V \pm 10\%$, unless otherwise noted)

Write cycle

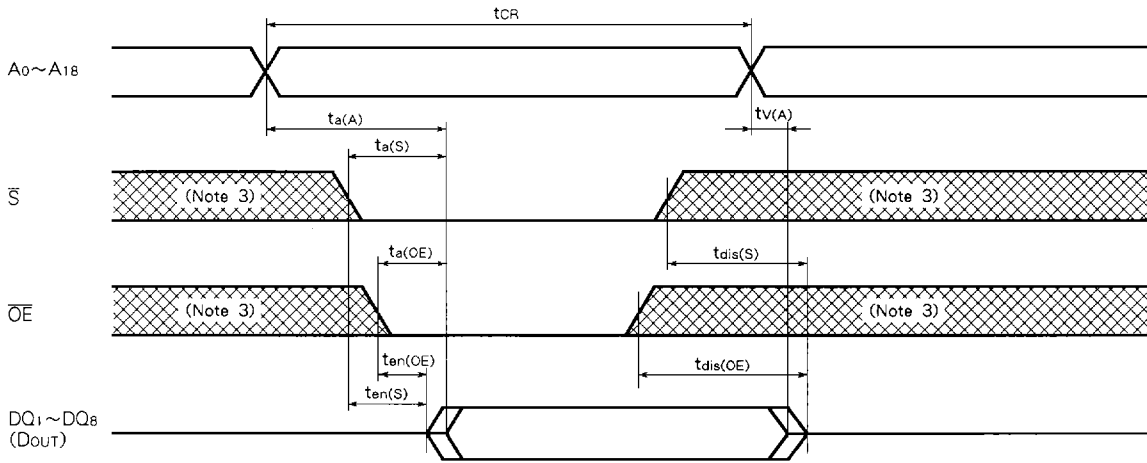
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		MH5128-70		MH5128-85		MH5128-10		MH5128-12		MH5128-15		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{CW}	Write cycle time	70		85		100		120		150		ns
$t_{w(W)}$	Write pulse width	45		55		65		75		85		ns
$t_{su(A)}$	Address set up time	0		0		0		0		0		ns
$t_{su(A-\bar{W}H)}$	Address set up time with respect to \bar{W} high	50		65		75		85		100		ns
$t_{su(S)}$	Chip select set up time	65		80		90		100		115		ns
$t_{su(D)}$	Data set up time	50		30		35		40		45		ns
$t_{h(D)}$	Data hold time	0		0		0		0		0		ns
$t_{rec(W)}$	Write recovery time	0		0		0		0		0		ns
$t_{dis(W)}$	Output disable time after \bar{W} low		20		25		30		35		40	ns
$t_{dis(OE)}$	Output disable time after \bar{OE} high		20		25		30		35		40	ns
$t_{en(W)}$	Output enable time after \bar{W} high	5		5		5		5		5		ns
$t_{en(OE)}$	Output enable time after \bar{OE} low	5		5		5		5		5		ns

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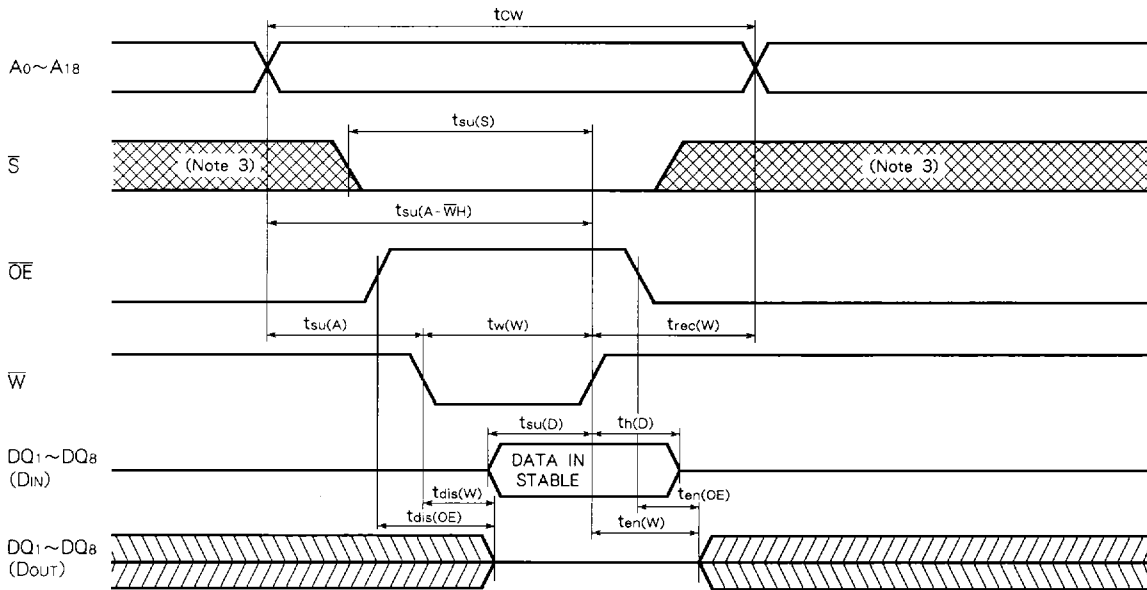
TIMING DIAGRAM

Read cycle



\bar{W} = "H" level

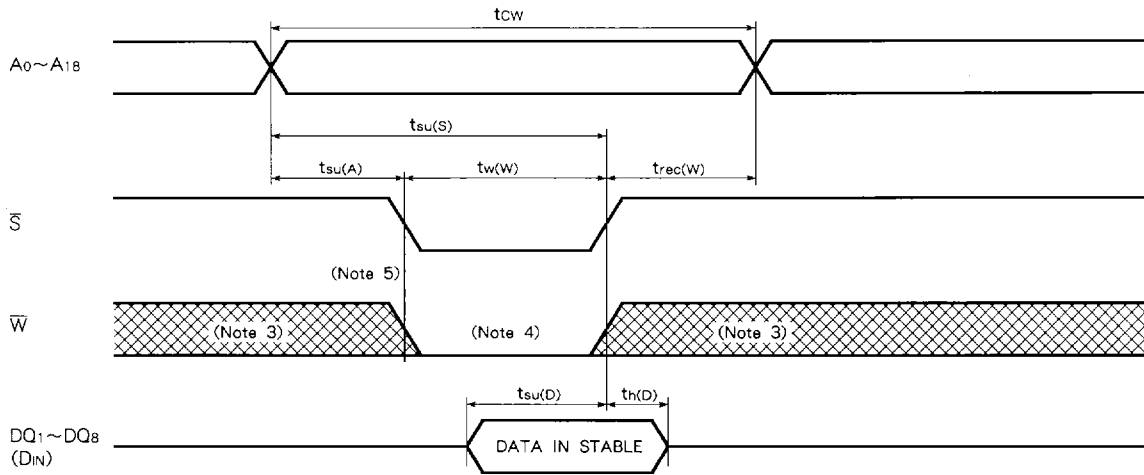
Write cycle (\bar{W} control)



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Write cycle (\bar{S} control)



- Note 3. Hatching indicates the state is don't care.
 4. Writing is executed in overlap of \bar{S} and \bar{W} low.
 5. If \bar{W} goes low simultaneously with or prior to \bar{S} , the output remains in the high-impedance state.
 6. Don't active inverted phase signal externally when DQ pin is in output mode.

POWER DOWN CHARACTERISTICS

ELECTRICAL CHARACTERISTICS (Ta = 0~70°C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V _{CC(PD)}	Power down supply voltage		2			V
V _{I(\bar{S})}}	Chip select input \bar{S}	2.2V ≤ V _{CC(PD)}	2.2			V
I _{CC(PD)}	Power down supply current	V _{CC} = 3V, $\bar{S} \geq V_{CC} - 0.2V$, A ₁₇ ~A ₁₈ = V _{CC} or GND Other inputs = 0~V _{CC}			250 90 (Note 7)	μA

Note 7. I_{CC(PD)} = 20 μA at Ta = 25°C.

* When \bar{S} is at 2.2V (V_{IH} min) and supply voltage is at any level between 4.5V and 2.4V, supply current is defined as I_{CC4}.

TIMING REQUIREMENTS (Ta = 0~70°C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
t _{su(PD)}	Power down setup time		0			ns
t _{trec(PD)}	Power down recovery time		5			ms

POWER DOWN CHARACTERISTICS

